



3D Packaging & Integration North America TC Chapter

NA Standards Fall Meeting 2025

Tuesday, October 14

Online via Official Virtual Technical Committee Chapter Meeting (OVTCCM)

13:00–14:30 Pacific

AGENDA

	Time
1 Welcome/Call to Order	13:00
1.1 Please log into www.svm.semi.org for voting	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Introductions	
1.4 Agenda Review	
2 Liaison Reports	13:15
2.1 Japan TC Chapter	
2.2 Taiwan TC Chapter	
3 Staff Report	13:25
4 Review of Previous Meeting Minutes	13:30
5 Ballot Review	13:35
5.1 Document 7368 — Reapproval of SEMI 3D12-1020, Guide for Measuring Flatness and Shape of Low Stiffness Wafers	
6 Task Force Updates	14:00
6.1 3DP&I Bonded Wafer Stacks and Inspection & Metrology Task Forces	
6.2 Panel Level Packaging (PLP) Panel Task Force	



	Time
7 Old Business	14:10
7.1 Five-Year Review (None)	
8 New Business	14:20
9 Action Item Review	14:25
Coordinate with Japan PIC and NA PLP Panel TF meeting. (Shoji/Steve/Rich)	
10 Next Meeting and Adjournment	14:30
10.1 The SEMI Standards NA Winter Meetings 2026 are tentatively scheduled for the week of February 23-26, 2026, to be held virtually via OVTCCM. Schedule details TBD. https://www.semi.org/en/products-services/standards .	

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NOTE:

Standards meetings are open to all, but you must be a SEMI Standards Program Member to attend.

If you are not a member, please register for the International SEMI Standards Program here:

<https://www.semi.org/standardsmembership>

STANDARDS VIRTUAL MEETING INFORMATION:

Please email Laura Nguyen, Lnguyen@semi.org, for teleconference information.